Please note that Cypress is an Infineon Technologies Company.
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

Cypress Semiconductor
Board/Module Qualification Report

QTP# 153903 VERSION*A
December 2018

FITTEC BOARD ASSEMBLY	
CYBLE-012011-00 CYBLE-012012-10 CYBLE-014008-00 CYBLE-022001-00 CYBLE-212019-00 CYBLE-212020-01 CYBLE-214009-00 CYBLE-214015-01 CYBLE-212023-10 CYBLE-222005-00 CYBLE-222014-01 CYBLE-202013-11 CYBLE-212006-01 CYBLE-202007-01	EZ-BLE PRoC and EZ-BLE PSoC Bluetooth® Low Energy Modules

FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
reliability@cypress.com or via a CYLINK CRM CASE

Prepared By:
Josephine Pineda (JYF)
Sr. Staff Reliability Engineer

Reviewed By:
Sandhya Chandrashekhar (SANC)
Principal Reliability Engineer

Approved By:
David Hoffman (DHH)
Reliability Director

PACKAGE/PRODUCT QUALIFICATION HISTORY

QTP Number	Description of Qualification Purpose	Date
153903	Qualification of New Contract Manufacturer (CM) FITTEC for BLE Module Manufacturing	April 2016

PRODUCT DESCRIPTION	
Qualification Purpose: Qualify New Contract Manufacturer (CM) FITTEC for BLE Module Manufacturing	
Marketing Part #:	CYBLE-012011-00/CYBLE-012012-10/CYBLE-014008-00 CYBLE-022001-00/CYBLE-212019-00/CYBLE-212020-01 CYBLE-214009-00/CYBLE-214015-01/CYBLE-212023-10 CYBLE-222005-00/CYBLE-222014-01/CYBLE-202013-11/ CYBLE-212006-01/CYBLE-202007-01
Device Description:	Trackpad Modules
Cypress Division:	Cypress Semiconductor Corporation – Data Communications Division

CYBLE-022001-00	
PSoC Device:	CYBL10563-68FNXI
Package Outline, Type, or Name:	SMT
Package Dimension:	10.00 mm x 10.00 mm x 1.80 mm
Package Lead Pitch:	0.76 mm
Board Material:	FR4
Board Dimension:	10.00 mm x 10.00 mm x 1.80 mm
Board Layers:	4
Surface Finish:	Electroless Nickel Immersion Gold (ENIG)
Solder Paste:	Alpha OM340
Name/Location of Assembly (prime) facility:	Fittec/Suzhou, China
Reflow Profile	Peak reflow 260C; maximum time at peak: 30 seconds.

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
Acoustic Microscopy	JEDEC JSTD-020	P
High Temperature Operating Life	MIL-STD 202 Method 108, Dynamic Operating Condition, Vcc Max = 3.3V, 85C	P
High Temperature Storage	MIL-STD 202 Method 103, 90C, no bias	P
Low Temperature Operating Life	MIL-STD 202 Method 108, Dynamic Operating Condition, Vcc Max = 3.3V, -40C	P
Low Temperature Storage	MIL-STD 202 Method 103, -50C, no bias	P
Mechanical Shock	MIL-STD 202 Method 213	P
Temperature Cycle	MIL-STD 202 Method 107, -40C to 85C	P
Temperature Humidity	MIL-STD 202 Method 106, 90C, 85%RH	P
Vibration	MIL-STD 202 Method 204	P

Reliability Test Data

QTP #: 153903

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC							
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (85C, 3.3V, Vcc Max)							
CYBLE-022001-00	0	0	FITTEC	168	22	0	
CYBLE-022001-00	0	0	FITTEC	168	22	0	
CYBLE-022001-00	0	0	FITTEC	168	22	0	
STRESS: HIGH TEMP STORAGE, 90C							
CYBLE-022001-00	0	0	FITTEC	168	15	0	
CYBLE-022001-00	0	0	FITTEC	168	15	0	
CYBLE-022001-00	0	0	FITTEC	168	15	0	
STRESS: LOW TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (-40C, 3.3V, Vcc Max)							
CYBLE-022001-00	0	0	FITTEC	168	22	0	
CYBLE-022001-00	0	0	FITTEC	168	22	0	
CYBLE-022001-00	0	0	FITTEC	168	22	0	
STRESS: LOW TEMPERATURE STORAGE, -50C							
CYBLE-022001-00	0	0	FITTEC	168	15	0	
CYBLE-022001-00	0	0	FITTEC	168	15	0	
CYBLE-022001-00	0	0	FITTEC	168	15	0	
STRESS: MECHANICAL SHOCK							
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
STRESS: TC COND. G – 40C TO 85C							
CYBLE-022001-00	0	0	FITTEC	100	15	0	
CYBLE-022001-00	0	0	FITTEC	100	15	0	
CYBLE-022001-00	0	0	FITTEC	100	15	0	

Reliability Test Data

QTP #: 153903

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: TEMPERATURE HUMIDITY, 90 C/85%RH							
CYBLE-022001-00	0	0	FITTEC	168	15	0	
CYBLE-022001-00	0	0	FITTEC	168	15	0	
CYBLE-022001-00	0	0	FITTEC	168	15	0	
STRESS: VIBRATION							
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	
CYBLE-022001-00	0	0	FITTEC	COMP	5	0	

Document History Page

Document Title: QTP# 153903: Qualification of New Contract Manufacturer (CM) FITTEC for BLE Module Manufacturing
Document Number: 002-17501

Rev.	ECN No.	Orig. of Change	Description of Change
**	5483846	JYF	Initial Spec Release.
*A	6416025	JYF	Updated CY logo, Reliability contact person and MPN coverage.